

## **C1206X112KATACTU**

Aliases (C1206X112KATAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 1,100 pF, 10%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	15 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		
Chip Size	1206	
L	3.3mm +/-0.4mm	
W	1.6mm +/-0.35mm 0.78mm +/-0.20mm	
Т		
S	1.5mm MIN	
В	0.6mm +/-0.25mm	

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В	0.6mm +/-0.25mm
Packaging Specifications	

	Specifications		
	Capacitance	1,100 pF	
	Measurement Condition	1 kHz 1.0Vrms	
	Tolerance	10%	
	Voltage DC	250 VDC	
	Dielectric Withstanding Voltage	625 VDC	
	Temperature Range	-55/+150°C	
	Temp. Coefficient	X8G	
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
	Dissipation Factor	0.1% 1 kHz 1.0Vrms	
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
	Insulation Resistance	100 GOhms	

Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C and 0 VI Applied (TCC)
Packaging Quantity	4000	Dissipation Factor

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